- Designed for Complementary Use with BDW94, BDW94A, BDW94B and BDW94C
- 80 W at 25°C Case Temperature
- 12 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 5 A

Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT
	BDW93		45	
Collector base valtage (I — 0)	BDW93A	.,	60	V
Collector-base voltage (I _E = 0)	BDW93B	V _{CBO}	80	
	BDW93C		100	
	BDW93		45	
Collector emitter veltage (I O)	BDW93A	.,	60	V
Collector-emitter voltage ($I_B = 0$)	BDW93B	V _{CEO}	80	
	BDW93C		100	
Emitter-base voltage			5	V
Continuous collector current			12	Α
Continuous base current			0.3	Α
Continuous device dissipation at (or below) 25°C case temperature (see Note 1)			80	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 2)			2	W
Operating junction temperature range			-65 to +150	°C
Storage temperature range			-65 to +150	°C
Operating free-air temperature range			-65 to +150	°C

NOTES: 1. Derate linearly to 150°C case temperature at the rate of 0.64 W/°C.

2. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.

BDW93, BDW93A, BDW93B, BDW93C NPN SILICON POWER DARLINGTONS

SEPTEMBER 1993 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT	
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 100 mA	I _B = 0	(see Note 3)	BDW93 BDW93A BDW93B BDW93C	45 60 80 100			V
I _{CEO}	Collector-emitter cut-off current	$V_{CB} = 40 \text{ V}$ $V_{CB} = 60 \text{ V}$ $V_{CB} = 80 \text{ V}$ $V_{CB} = 80 \text{ V}$	$I_{B} = 0$ $I_{B} = 0$ $I_{B} = 0$ $I_{B} = 0$		BDW93 BDW93A BDW93B BDW93C			1 1 1	mA
I _{CBO}	Collector cut-off current	V _{CB} = 45 V V _{CB} = 60 V V _{CB} = 80 V V _{CB} = 100 V V _{CB} = 45 V V _{CB} = 60 V V _{CB} = 80 V	I _E = 0	$T_{C} = 150^{\circ}\text{C}$ $T_{C} = 150^{\circ}\text{C}$ $T_{C} = 150^{\circ}\text{C}$ $T_{C} = 150^{\circ}\text{C}$	BDW93 BDW93A BDW93B BDW93C BDW93 BDW93A BDW93B BDW93C			0.1 0.1 0.1 0.1 5 5 5	mA
I_{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0					2	mA
h _{FE}	Forward current transfer ratio	0_	$I_{C} = 3 A$ $I_{C} = 10 A$ $I_{C} = 5 A$	(see Notes 3 and	i 4)	1000 100 750		20000	
V _{CE(sat)}	Collector-emitter saturation voltage	$I_B = 20 \text{ mA}$ $I_B = 100 \text{ mA}$	$I_{C} = 5 A$ $I_{C} = 10 A$	(see Notes 3 and 4)				2 3	V
V _{BE(sat)}	Base-emitter saturation voltage	$I_B = 20 \text{ mA}$ $I_B = 100 \text{ mA}$	$I_C = 5 A$ $I_C = 10 A$	(see Notes 3 and 4)				2.5 4	V
V _{EC}	Parallel diode forward voltage	I _E = 5 A I _E = 10 A	$I_{B} = 0$ $I_{B} = 0$					2 4	V

NOTES: 3. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

	PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.56	°C/W
$R_{\theta,JA}$	Junction to free air thermal resistance			62.5	°C/W

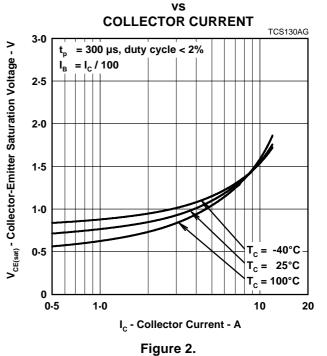
^{4.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN COLLECTOR CURRENT TCS130AE 50000 = -40°C 25°C = 100°C h_{FE} - Typical DC Current Gain 000 000 3 V = 300 μs, duty cycle < 2% 100 0.5 1.0 10 20 I_c - Collector Current - A

Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE



BASE-EMITTER SATURATION VOLTAGE

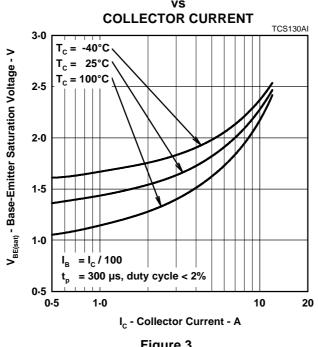


Figure 3.



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION

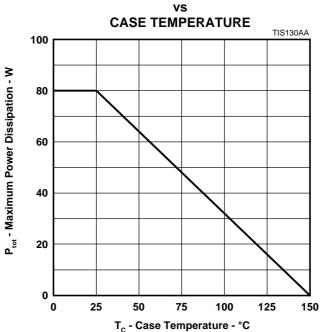


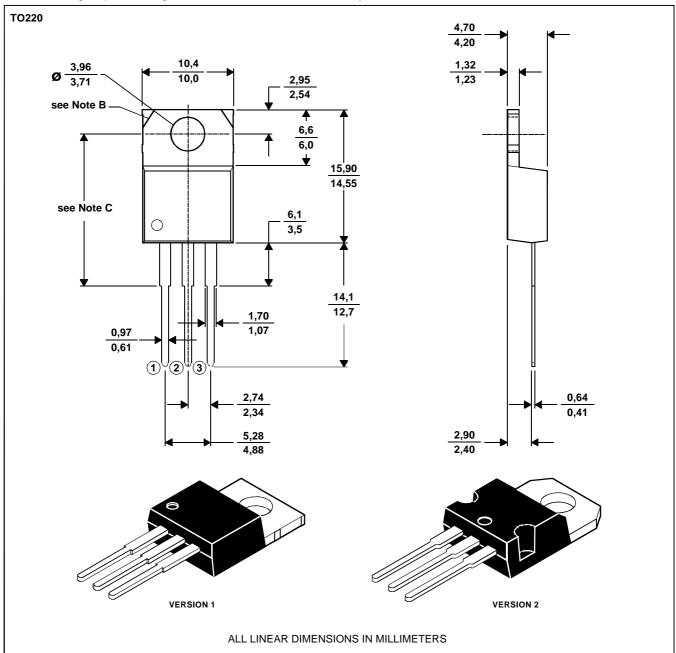
Figure 4.

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. MDXXBE



BDW93, BDW93A, BDW93B, BDW93C NPN SILICON POWER DARLINGTONS

SEPTEMBER 1993 - REVISED MARCH 1997

IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited